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cont

4 a separate lead rail adjacent the leadframe, the lead rail comprising a
5 plurality of leads and a groove;
6 a bumped die including solder bumps on a top side, the bumped die being
7 attached to the leadframe such that the solder bumps contact the source and gate
8 connections; and C
9 a copper clip attached to a backside of the bumped die such that the copper
10 clip contacts drain regions of the bumped die and the lead rail groove;
11 wherein the lead rail and leadframe are oriented such that their respective
12 plurality of leads extend in opposing directions.

REMARKS

Claims 5 and 6 are pending.

Claims 5 and 6 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Temple et al. (U.S. Patent No. 5,103,290). This rejection is respectfully traversed and reconsideration is respectfully requested.

Applicant has amended claim 5 to make it clear that the chip device includes a separate lead rail adjacent the leadframe and that both the leadframe and the lead rail include a plurality of leads. A copper clip is attached to a backside of a bumped die such that the copper clip contacts drain regions of the bumped die and the lead rail groove. The lead rail and leadframe are oriented such that their respective plurality of leads extend in opposing directions. It is respectfully submitted that Temple et al. do not disclose such a chip device. Temple et al. do not disclose a separate lead rail adjacent a lead frame wherein both include a plurality of leads. Temple et al. do not disclose a chip device that includes a cooper clip that contacts the lead rail's groove. Finally, since Temple et al. do not disclose a plurality of leads on a leadframe and a plurality of leads on a lead rail, they also do not disclose that the respective leads of the leadframe and the lead rail extend in opposing directions.

Accordingly, it is respectfully submitted that Temple et al. do not teach, disclose, or even suggest a chip device as recited in amended claim 5 and therefore, it is

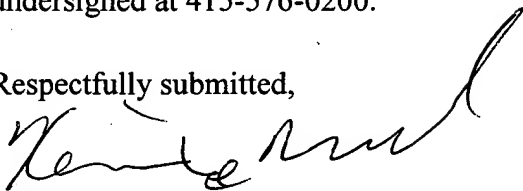
respectfully submitted that claim 5 is allowable. Claim 6 depends on claim 5 and therefore is allowable for at least the reasons claim 5 is allowable.

CONCLUSION

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance. The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 415-576-0200.

Respectfully submitted,



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

- 1 5. (Twice Amended) A chip device comprising:
2 a leadframe including source and gate connections, and a plurality of
3 leads;
4 a separate lead rail adjacent the leadframe, the lead rail comprising a
5 plurality of leads and a groove;
6 a bumped die including solder bumps on a top side, the bumped die being
7 attached to the leadframe such that the solder bumps contact the source and gate
8 connections; and
9 a copper clip attached to a backside of the bumped die such that the copper
10 clip contacts drain regions of the bumped die and [a] the lead rail groove;
11 wherein the lead rail and leadframe are oriented such that their respective
12 plurality of leads extend in opposing directions.